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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Min-Lung HUANG et al. Confirmation No: 8687
Appl. No. : 10/820,855
Filed : April 9, 2004
Title : Under Bump Metallization Structure Of A Semiconductor Wafer

TC/A.U. : 2814
Examiner : A. Kalam
Docket No.: HUAN3262/REF
Customer No: 23364

PETITION FOR EXTENSION OF TIME

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Applicants request that the period for response to the outstanding official action in this case be extended pursuant to 37 CFR 1.136 (a) for ONE (1) month to December 27, 2007.

The fee set in 37 CFR 1.17(a)(1) for a one month extension of time is \$120.00 and a check in this amount is submitted herewith. Please charge any additional fee required for this extension to Deposit Account No. 02-0200.

Respectfully submitted,
BACON & THOMAS, PLLC

By: Scott A. Brairton
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December 27, 2007